CEP603AL/CEB603AL

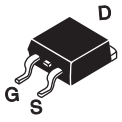
March 1998

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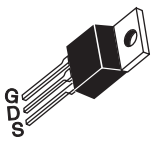
N-Channel Logic Level Enhancement Mode Field Effect Transistor

FEATURES

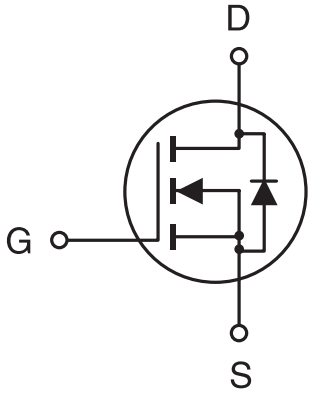
- 30V , 25A , $R_{DS(ON)}$=22mΩ @V_{GS}=10V.
  $R_{DS(ON)}$=40mΩ @V_{GS}=4.5V.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handling capability.
- TO-220 & TO-263 package.



CEB SERIES
TO-263(DD-PAK)



CEP SERIES
TO-220



ABSOLUTE MAXIMUM RATINGS (Tc=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous @T_J=125°C	I_D	25	A
-Pulsed	I_{DM}	100	A
Drain-Source Diode Forward Current	I_S	25	A
Maximum Power Dissipation @Tc=25°C	P_D	60	W
Derate above 25°C		0.4	W/°C
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to 175	°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.5	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W

ELECTRICAL CHARACTERISTICS (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V, I_D=250μA	30			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=24V, V_{GS}= 0V			10	μA
Gate-Body Leakage	I_{GSS}	V_{GS}=±20V, V_{DS}=0V			±100	nA
ON CHARACTERISTICS[a]						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D= 250μA	1	1.6	3	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS} = 10V, I_D= 25A		16	22	mΩ
		V_{GS} = 4.5V, I_D= 10A		24	40	mΩ
On-State Drain Current	$I_{D(ON)}$	V_{GS} = 10V, V_{DS} = 10V	60			A
Forward Transconductance	g_{FS}	V_{DS} = 10V, I_D = 25A		35		S
DYNAMIC CHARACTERISTICS[b]						
Input Capacitance	C_{ISS}	V_{DS} =15V, V_{GS} = 0V f =1.0MHz		706	920	pF
Output Capacitance	C_{OSS}			360	470	pF
Reverse Transfer Capacitance	C_{RSS}			95	130	pF
SWITCHING CHARACTERISTICS[b]						
Turn-On Delay Time	$t_{D(ON)}$	V_{DD} = 15V, I_D = 25A, V_{GS} = 10V, V_{GEN} =24Ω		20	23	ns
Rise Time	t_r			70	110	ns
Turn-Off Delay Time	$t_{D(OFF)}$			90	150	ns
Fall Time	t_f			85	130	ns
Total Gate Charge	Q_g	V_{DS} =10V, I_D = 25A, V_{GS} =10V		21	40	nC
Gate-Source Charge	Q_{gs}			6		nC
Gate-Drain Charge	Q_{gd}			2		nC

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ELECTRICAL CHARACTERISTICS (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS [a]						
Diode Forward Voltage	V_{SD}	V_{GS} = 0V, Is =25A		0.9	1.3	V

Notes

a.Pulse Test:Pulse Width ≤300 μs, Duty Cycle ≤ 2%.

b.Guaranteed by design, not subject to production testing.

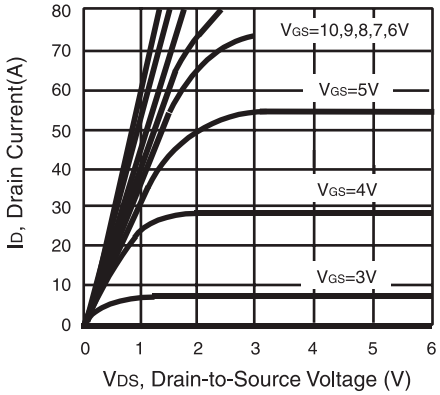


Figure 1. Output Characteristics

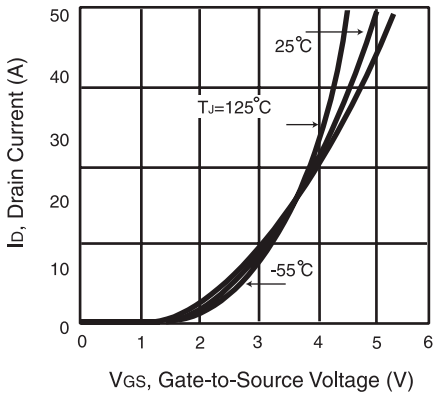


Figure 2. Transfer Characteristics

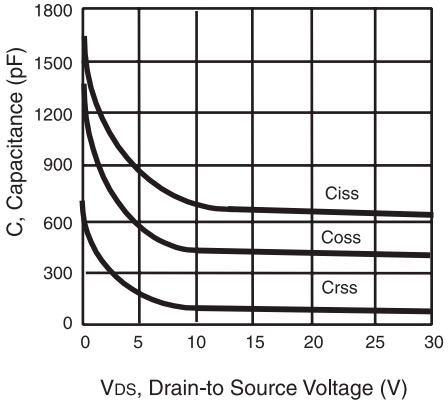


Figure 3. Capacitance

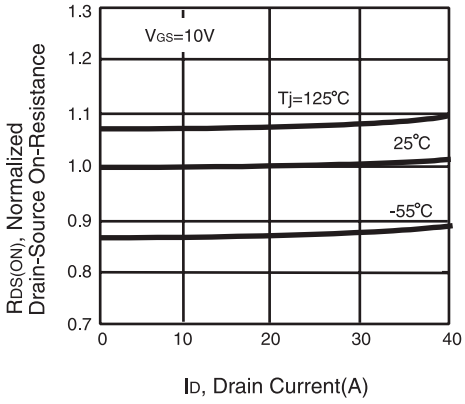


Figure 4. On-Resistance Variation with Drain Current and Temperature

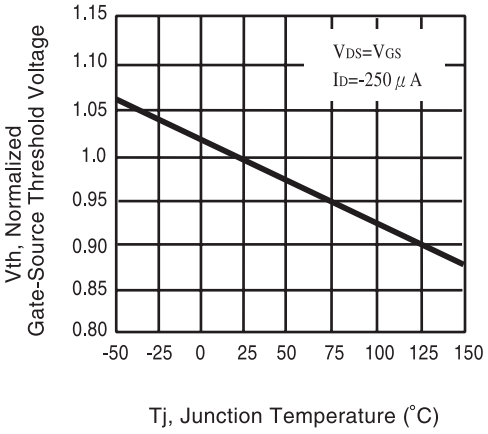


Figure 5. Gate Threshold Variation with Temperature

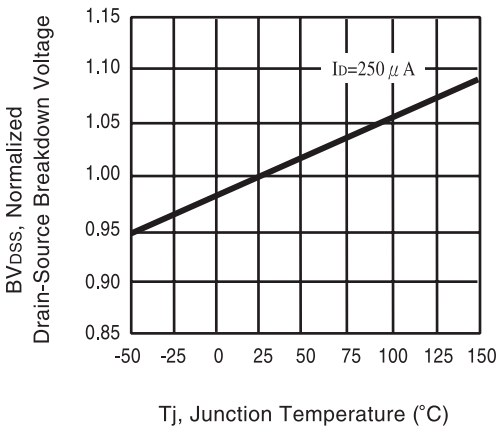


Figure 6. Breakdown Voltage Variation with Temperature

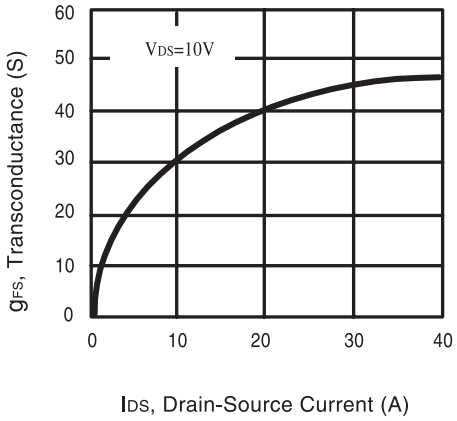


Figure 7. Transconductance Variation with Drain Current

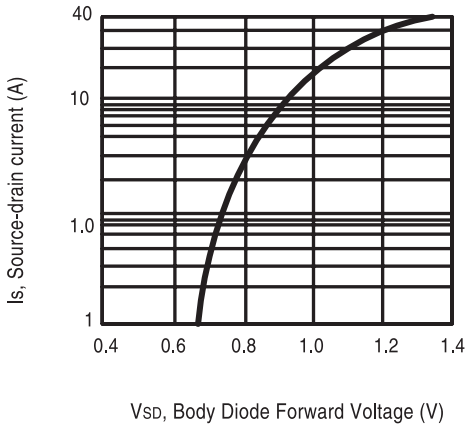


Figure 8. Body Diode Forward Voltage Variation with Source Current

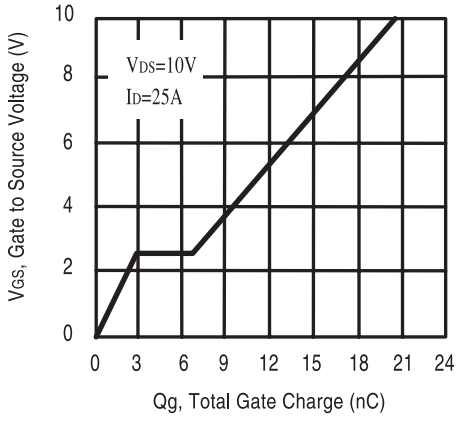


Figure 9. Gate Charge

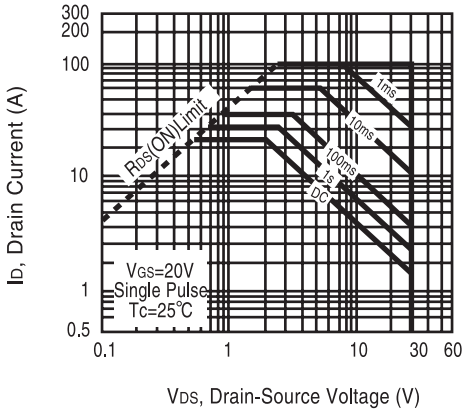


Figure 10. Maximum Safe Operating Area

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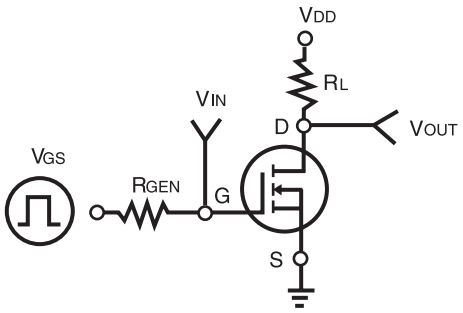


Figure 11. Switching Test Circuit

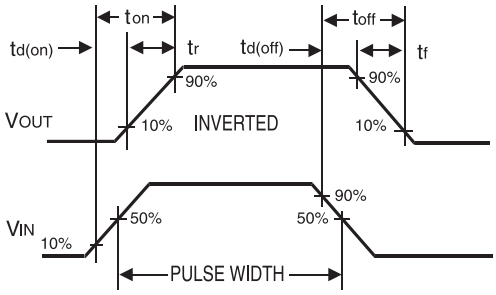


Figure 12. Switching Waveforms

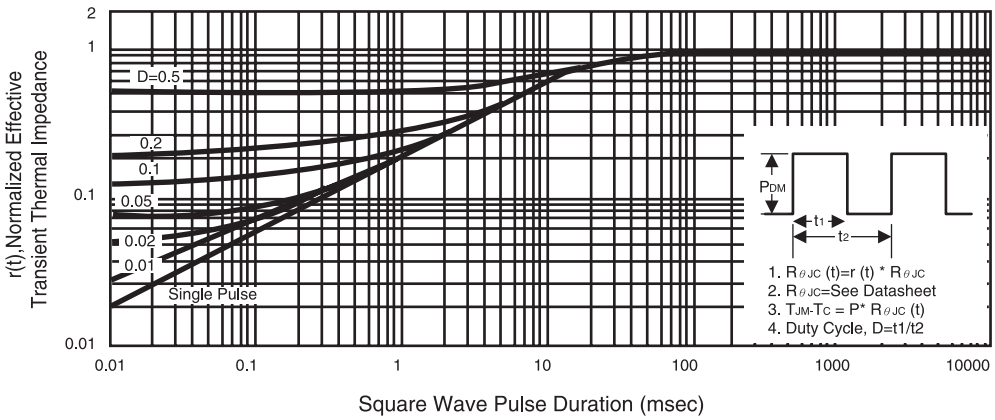


Figure 13. Normalized Thermal Transient Impedance Curve